

Title (en)

POWER MODULE, POWER CONVERTER AND DRIVE ARRANGEMENT WITH A POWER MODULE

Title (de)

LEISTUNGSMODUL, STROMRICHTER UND ANTRIEBSANORDNUNG MIT EINEM LEISTUNGSMODUL

Title (fr)

MODULE DE PUISSANCE, CONVERTISSEUR ET ENSEMBLE D'ENTRAÎNEMENT POURVU D'UN MODULE DE PUISSANCE

Publication

**EP 2989868 A1 20160302 (DE)**

Application

**EP 14722569 A 20140417**

Priority

- DE 102013207507 A 20130425
- EP 2014057875 W 20140417

Abstract (en)

[origin: WO2014173801A1] A power module (LM) is disclosed for a power converter (SR), which power module (LM) has: – a first busbar (SS1) with a first surface (O31) and a second surface (O 32) lying opposite the first surface (O31), – a first semiconductor component (H1) on the first surface (O31) of the first busbar (SS1), which semiconductor component (H1) has a first surface (O11) with a first electrical surface contact connection (K11) and is connected, via the first surface contact connection (K11), to the first surface (O31) of the first busbar (SS1) in an electrically conductive and mechanical fashion over an area, and – a second semiconductor component (H2) on the second surface (O32) of the first busbar (SS1), which semiconductor component (H2) has a first surface (O21) with a first electrical surface contact connection (K21) and is connected, via the first surface contact connection (K21) of the second semiconductor component (H2), to the second surface (O32) of the first busbar (SS1) in an electrically conductive and mechanical fashion over an area.

IPC 8 full level

**H05K 7/14** (2006.01); **H01L 23/495** (2006.01); **H01L 25/07** (2006.01)

CPC (source: EP US)

**H01L 23/49537** (2013.01 - EP US); **H01L 23/49548** (2013.01 - EP US); **H01L 23/49562** (2013.01 - EP US); **H01L 23/49568** (2013.01 - EP US); **H01L 23/49575** (2013.01 - EP US); **H02B 1/20** (2013.01 - US); **H02M 1/08** (2013.01 - US); **H05K 7/1432** (2013.01 - US); **H05K 7/14329** (2022.08 - EP); **H01L 24/06** (2013.01 - EP US); **H01L 24/29** (2013.01 - EP US); **H01L 24/32** (2013.01 - EP US); **H01L 24/33** (2013.01 - EP US); **H01L 2224/04026** (2013.01 - EP US); **H01L 2224/06181** (2013.01 - EP US); **H01L 2224/291** (2013.01 - EP US); **H01L 2224/32245** (2013.01 - EP US); **H01L 2224/33181** (2013.01 - EP US); **H01L 2924/1203** (2013.01 - EP US); **H01L 2924/13055** (2013.01 - EP US); **H01L 2924/1306** (2013.01 - EP US); **H01L 2924/13091** (2013.01 - EP US)

Citation (search report)

See references of WO 2014173801A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**DE 102013207507 B3 20140724**; CN 105325066 A 20160210; EP 2989868 A1 20160302; JP 2016523069 A 20160804; US 10027094 B2 20180717; US 2016105004 A1 20160414; WO 2014173801 A1 20141030

DOCDB simple family (application)

**DE 102013207507 A 20130425**; CN 201480023544 A 20140417; EP 14722569 A 20140417; EP 2014057875 W 20140417; JP 2016509402 A 20140417; US 201414787043 A 20140417